

# 微機電系統簡介

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<http://mdl.pme.nthu.edu.tw>



# 前言



## About MEMS



1 mm

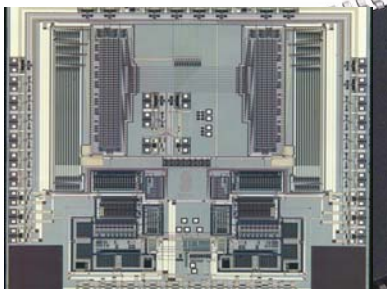


精尖動機系微機電系統實驗室

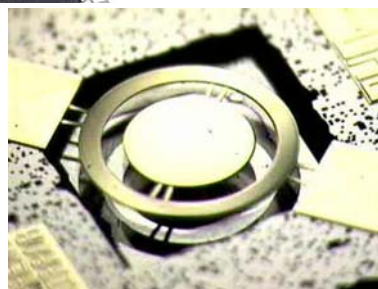


## What's MEMS

IC



MEMS



<http://www.aztex.biz/general-computer/integrated-circuit-work/>

Texas Instruments Inc.

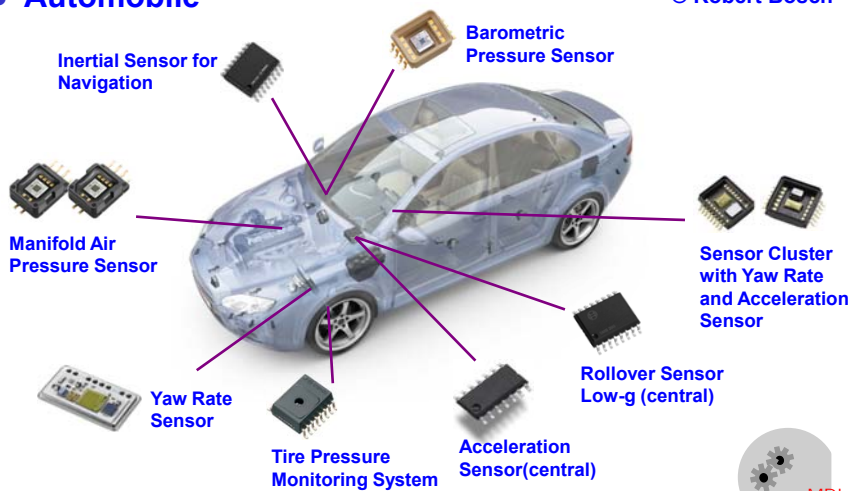
MDL



## Where's MEMS

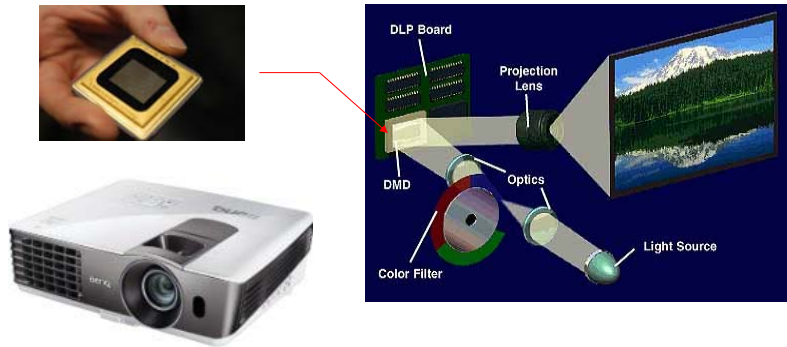
### • Automobile

© Robert Bosch



## Where's MEMS

- Before 2000 – inkjet printer, projector



Texas Instruments Inc.



## Where's MEMS

- 2006~2013 – consumer electronics



Wii

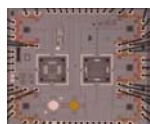
Smart phone

Wearable



## Where's MEMS

- MEMS Devices in volume in 2013 (from Yole)



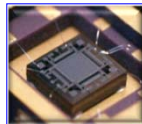
M sensor



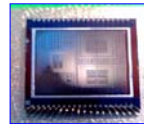
Humidity sensor



Microphone



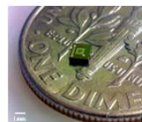
G sensor



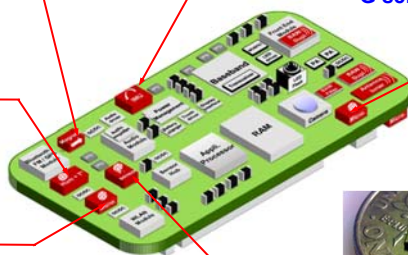
Gyro



Microphone



P sensor



Sensors in Smartphone, Yole report



## Where's MEMS

- Internet of Things (IoT)



### Smart Home

"The integration of technology and services through home networking for a better quality of living"

Situational Awareness

Environmental Sensing

Home control and automation

Remote Patient Monitoring

Remote surveillance & Security

Energy management



Body Gateway



Remote Surveillance



Smart Meter



Home Controller & Energy Display



Home Gateway



Smart Plug



Gas Meter



Renewable Energies



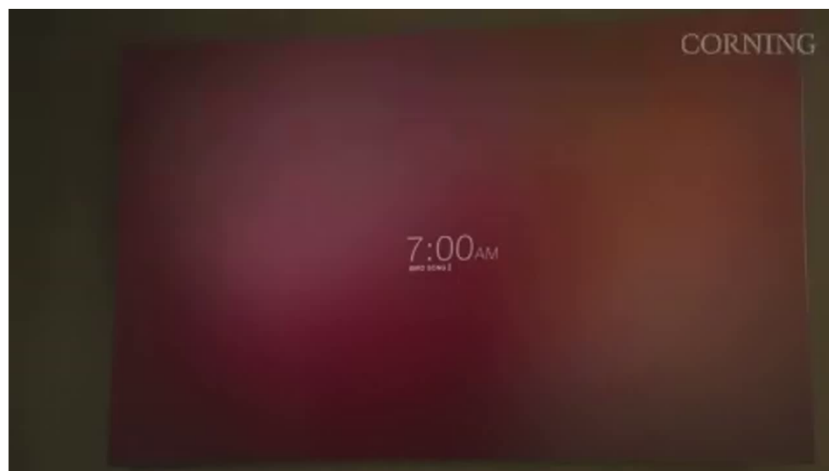
## Corning - A Day Made of Glass



<http://www.corning.com/index.aspx>



## Corning - A Day Made of Glass



<http://www.corning.com/index.aspx>



## Drone



Lightweight yet robust design.

<http://www.parrot.com/>



## Drone



<http://www.parrot.com/>



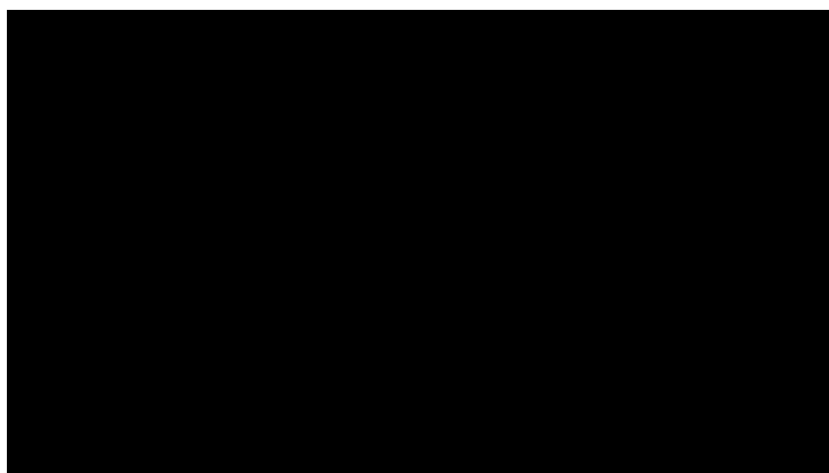
## Smart Ball



<http://micoach.adidas.com/>



## Smart Ball



<http://micoach.adidas.com/>





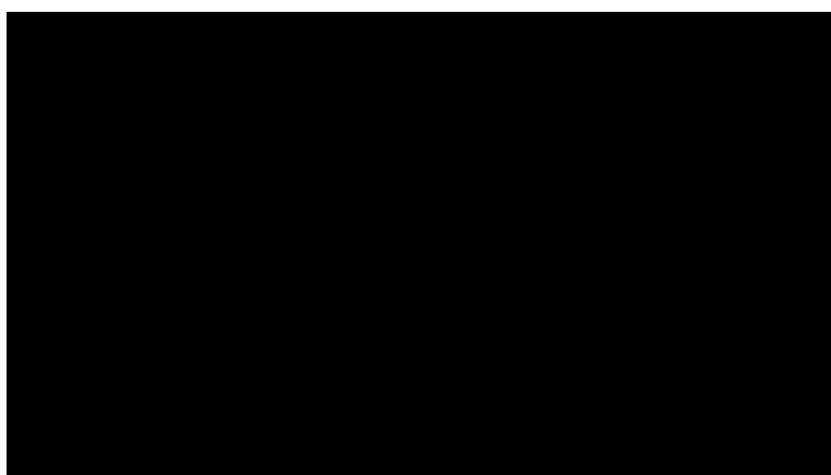
## Smart Earphone



<http://www.bragi.com/>



## Smart Earphone

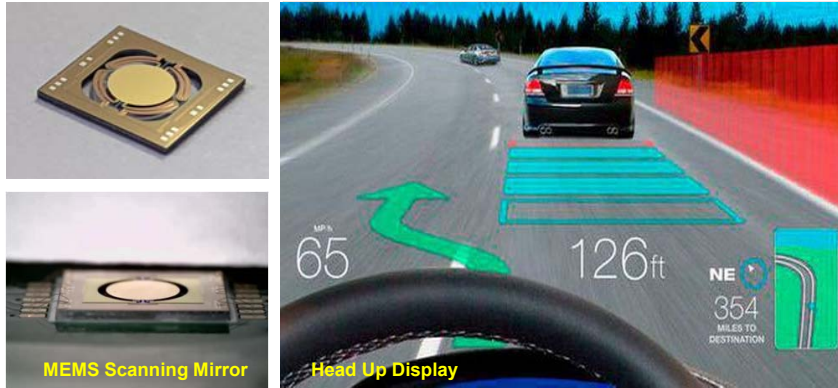


<http://www.bragi.com/>



## MEMS Scanning Mirror

- AR HUD, also for AR Glasses of Metaverse



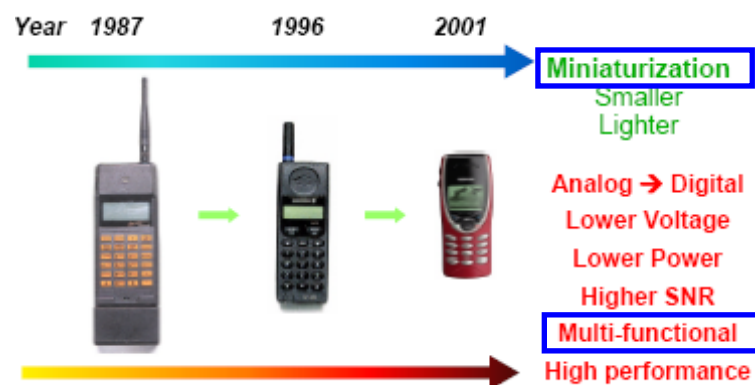
Cheng, Liu and Fang, 2022

<https://reurl.cc/EzozDv>



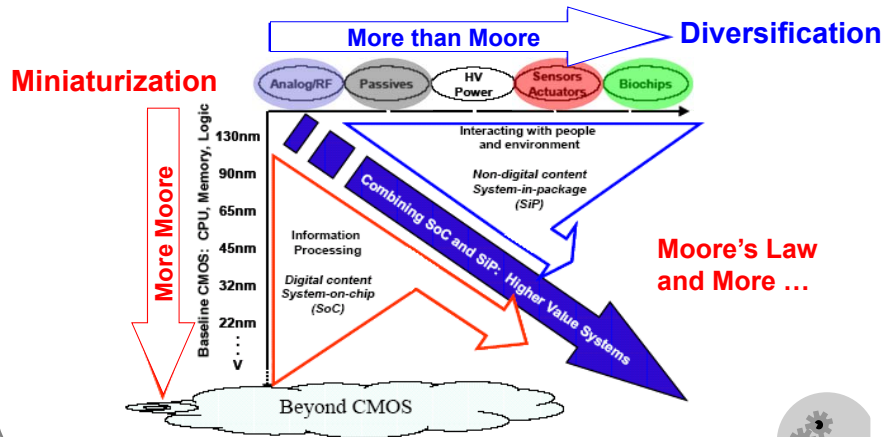
## Why MEMS

- Small and Smart



## Why MEMS

- Small and Smart
- Add value to the existing CMOS tech



Source: ITRS Roadmap 2005, [www.itrs.net](http://www.itrs.net)



## 平面加工技術

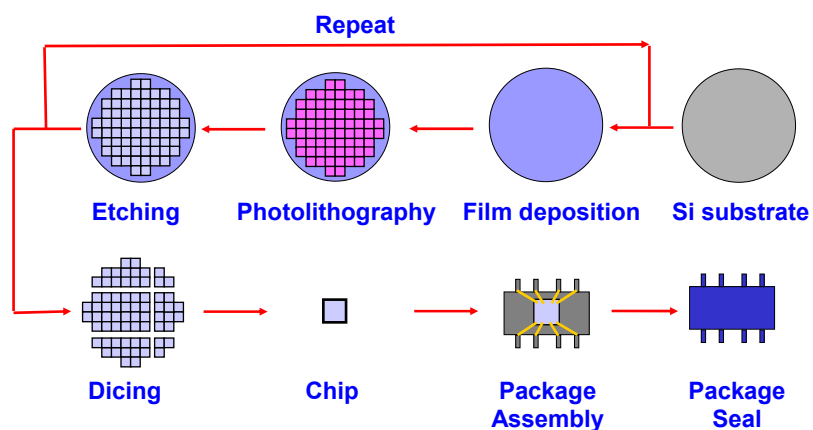


## Planar Technologies

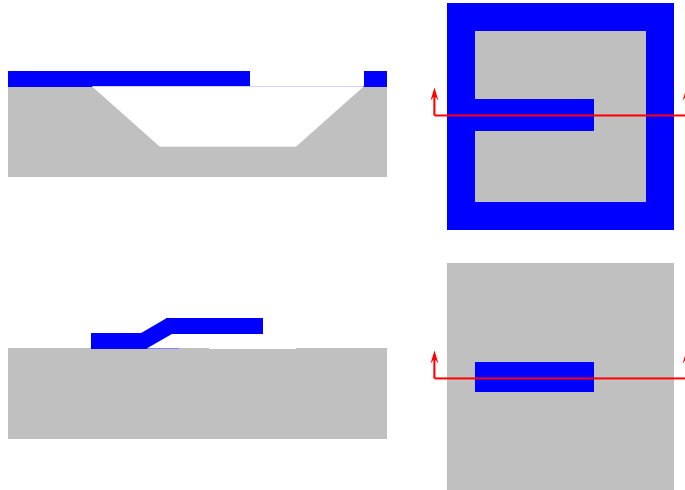
- IC : TSMC, UMC, Vanguard, ...
- LED/VCSEL/Diode laser : Liteon, Epistar,...
- TFT-LCD : AUO, Chimei-Innolux, ...
- Magnetic recording head : Seagate, WD, ...
- **MEMS : TSMC, UMC, APM, ...**



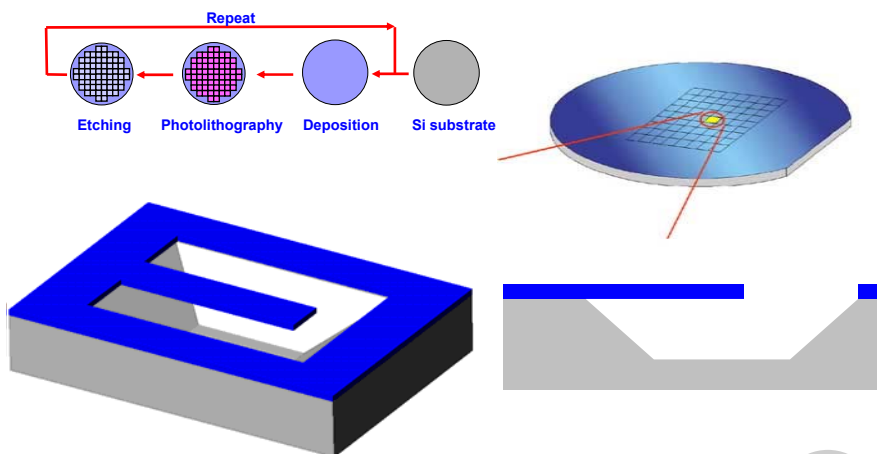
## Semiconductor processes



## Suspended MEMS Structures

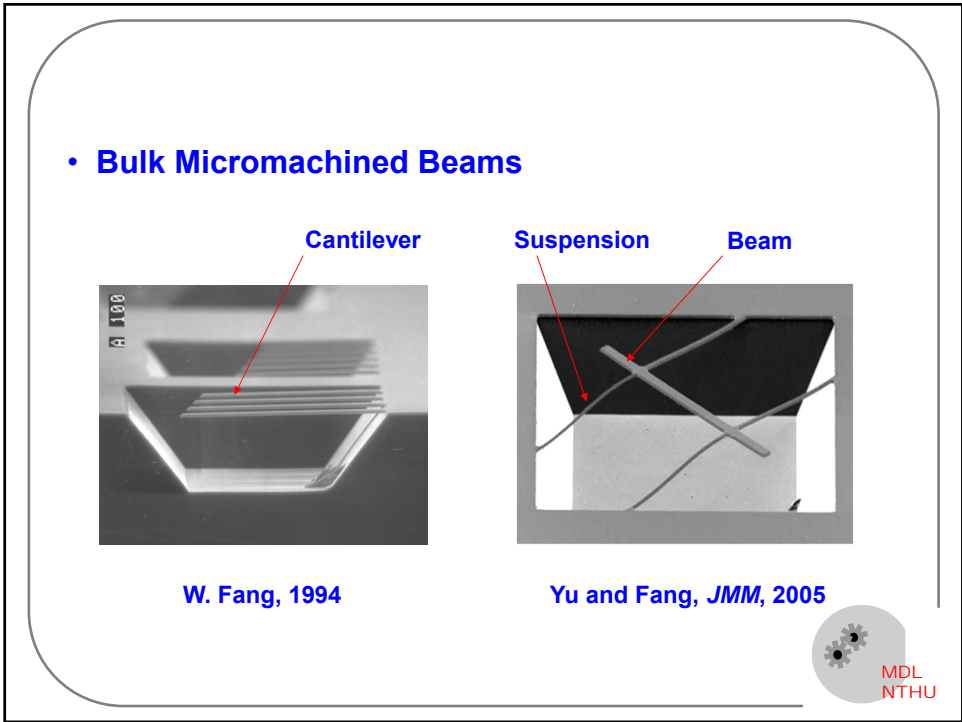
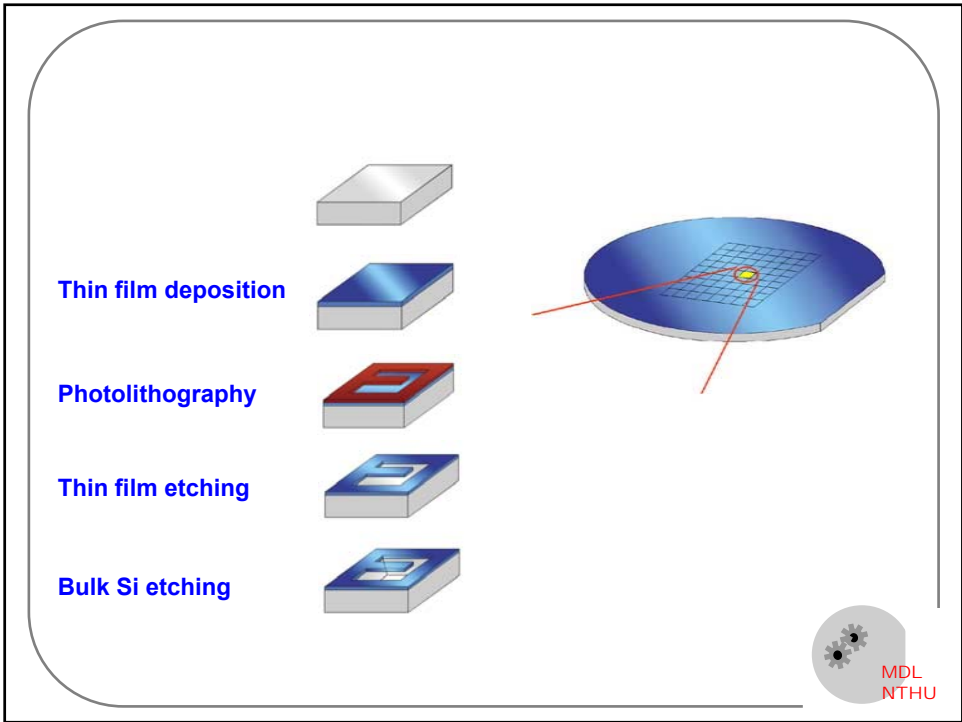


## Bulk Micromachining

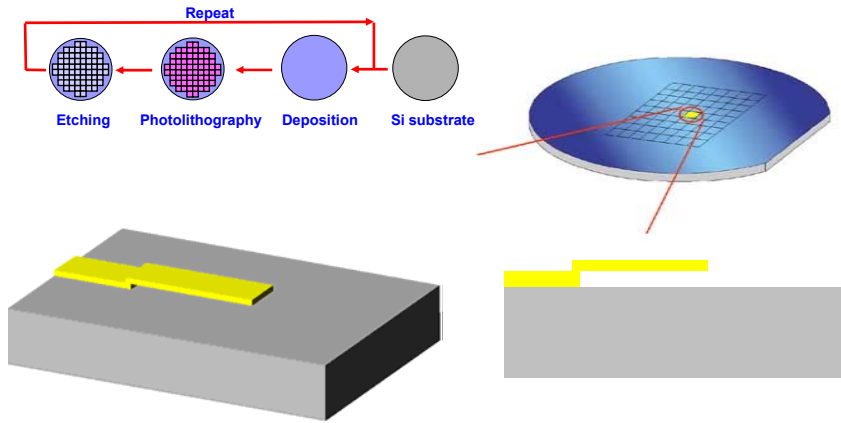


MEMS Manufacturing Technology





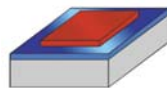
# Surface Micromachining



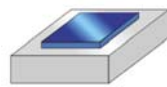
Lithography, Deposition, Etching



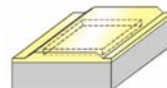
Photolithography



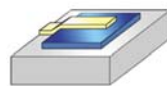
1st film etching



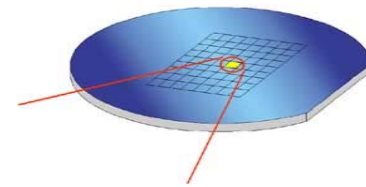
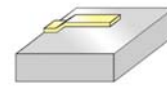
2nd film deposition



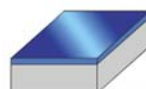
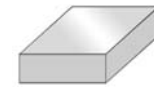
Photolithography & 2nd film etching



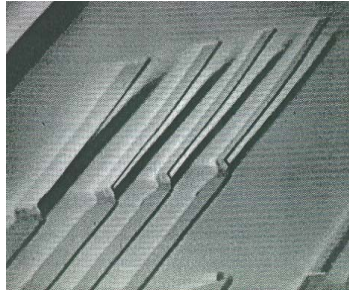
1st film removing



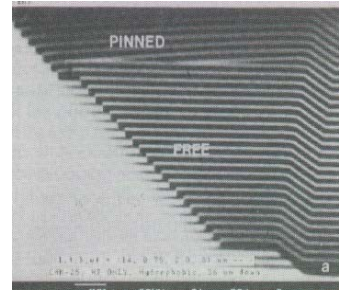
1st film deposition



- **Surface Micromachined Beams**



Howe and Muller, 1983



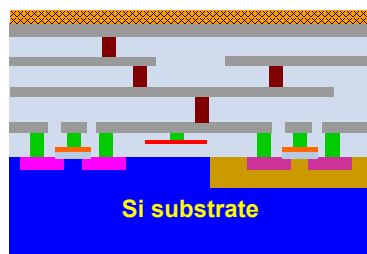
Mastrangelo and Hsu, 1993



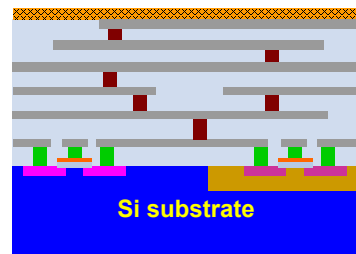
## Semiconductor Devices

- **Examples: by CMOS processes at TSMC, UMC, etc...**

0.35 $\mu$ m 2P4M CMOS process

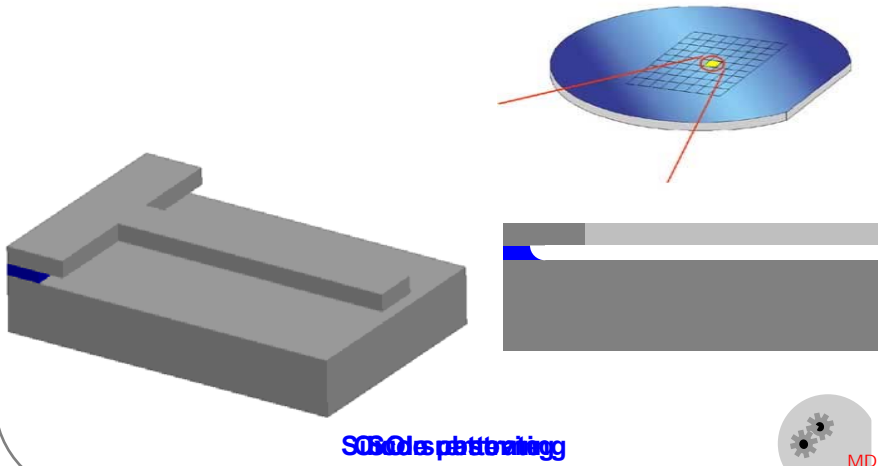


0.18 $\mu$ m 1P6M CMOS process



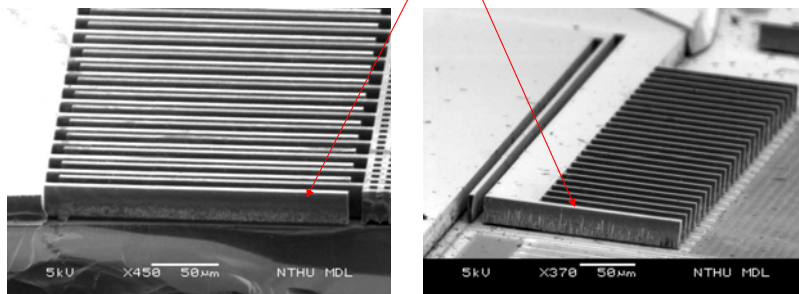


## SOI Micromachining



### • SOI Micromachined Beams

30 $\mu$ m thick beam



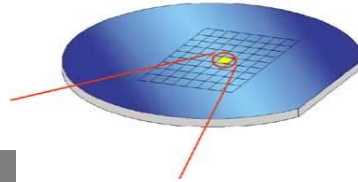
MDL



## Cavity SOI Micromachining



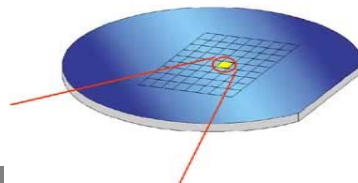
BuS

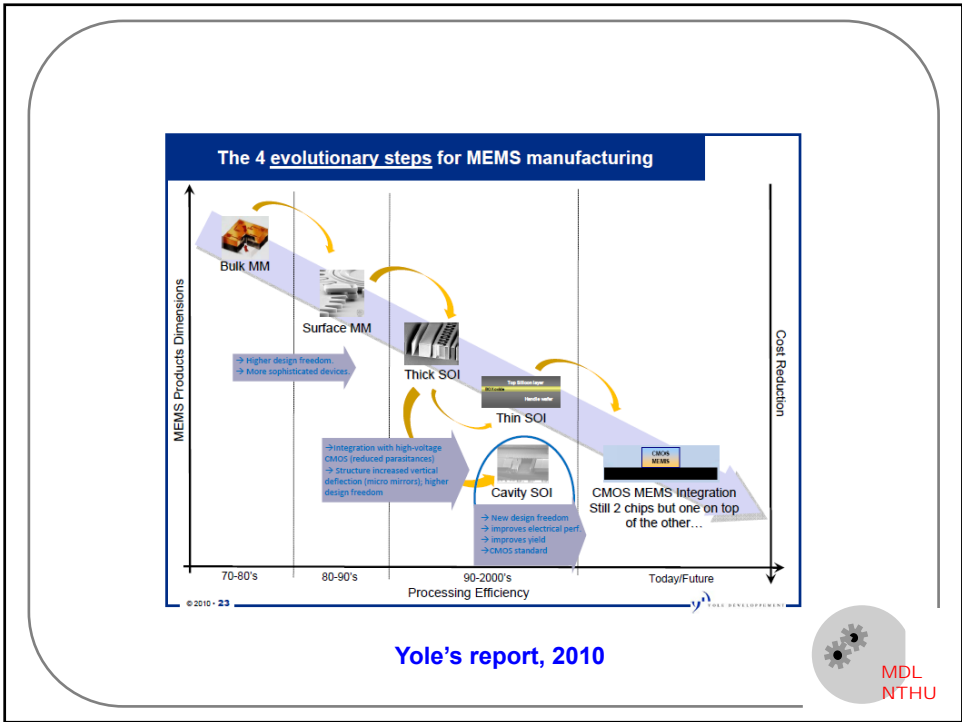


## CMOS SOI Micromachining



CMOS





**關鍵元件**

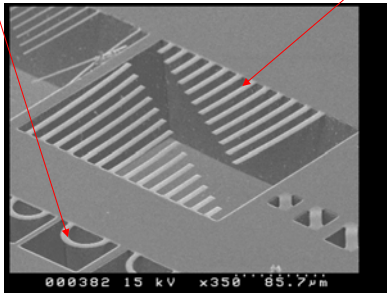
MDL NTHU

## Passive component

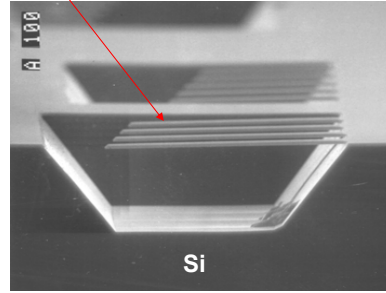
- Cantilever, suspension - springs

Semi-circular suspension

Cantilever



T. Tzou and W. Fang, 1999



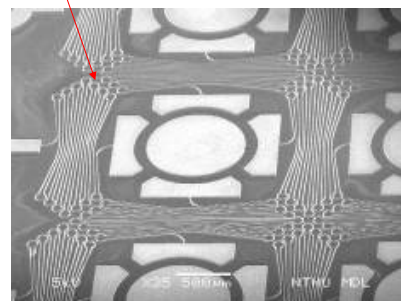
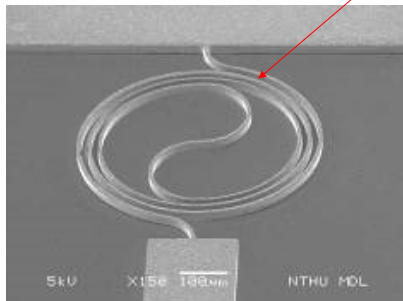
W. Fang, 1994



## Passive component

- Curved beam - spring

Curved beam

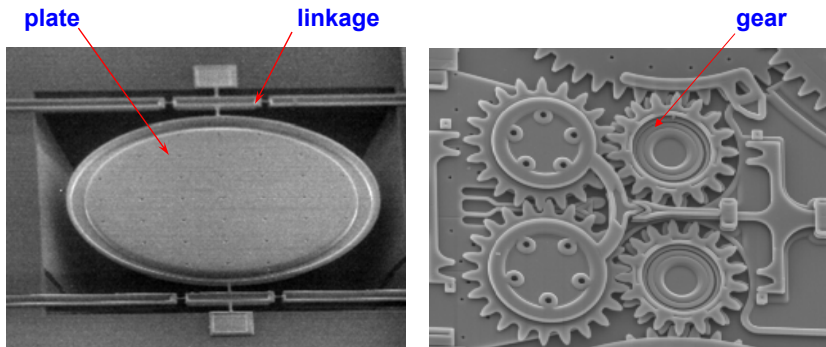


W.-L. Sung and W. Fang, 2014



## Passive component

- Plate, linkage, gear



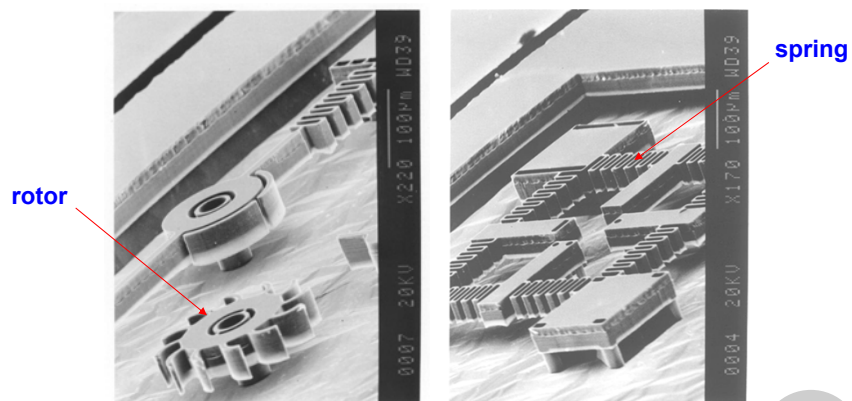
H.-Y. Lin and W. Fang, 2000

Sandia National Lab



## Passive component

- Gear, rotor, linkage

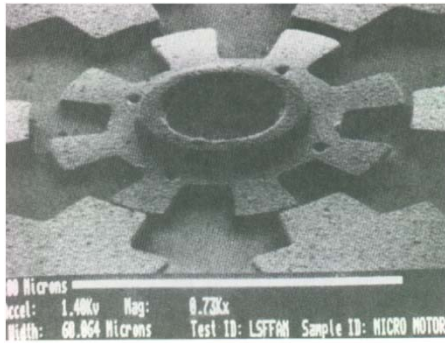


J. Hsieh and W. Fang, 2000



## Active component

- Angular electrostatic actuator - motor

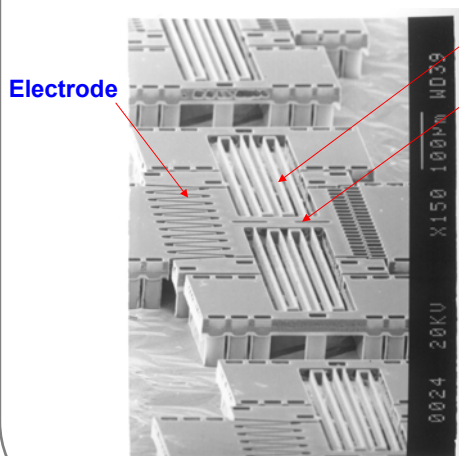


L.-S. Fan, et.al., Int. Electron Devices meeting, 1988



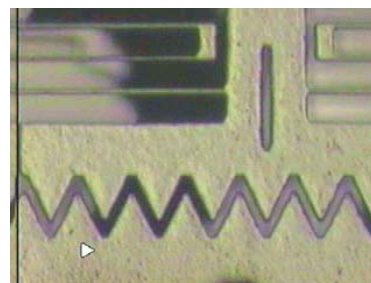
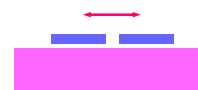
## Active component

- Linear electrostatic actuator



Spring

Moving stage

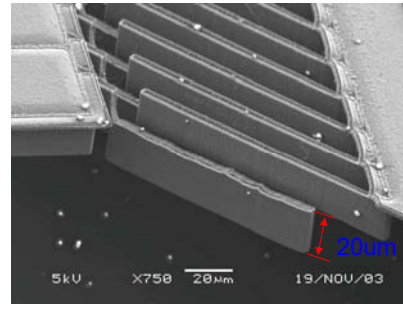
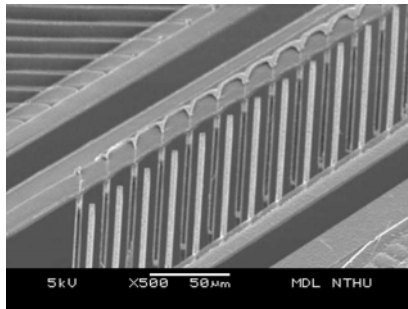
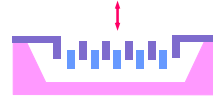


J. Hsieh and W. Fang, 2000



## Active component

- Linear electrostatic actuator



M. Wu and W. Fang, 2005



## Active component

- Angular electrostatic actuator

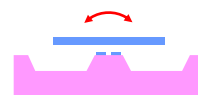
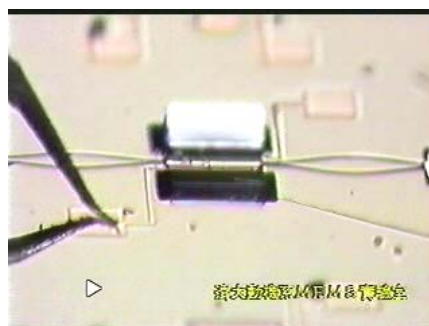
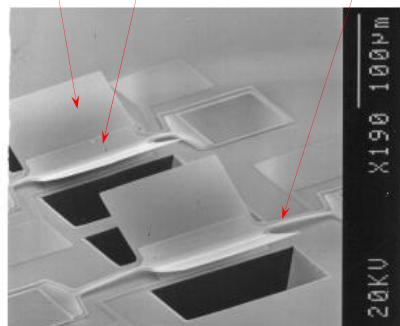


Plate Electrode Spring

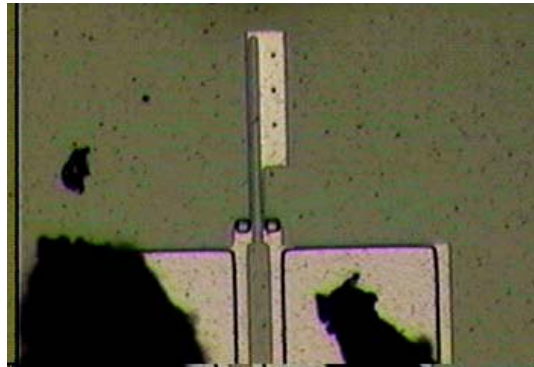


J. Hsieh and W. Fang, *Sensors and Actuators A*, 2000



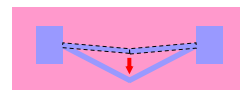
## Active component

- Linear thermal actuator



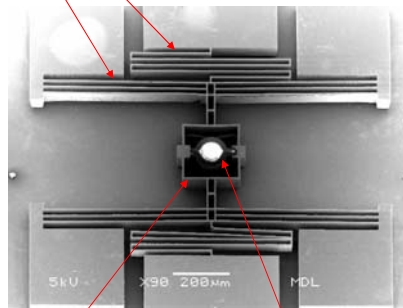
## Active component

- Linear thermal actuator



Spring (passive)

V-beam actuator (active)



Supporting frame (passive)

Lens (passive)

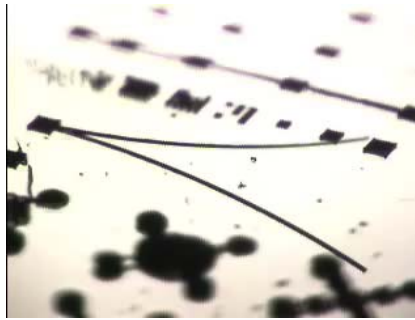
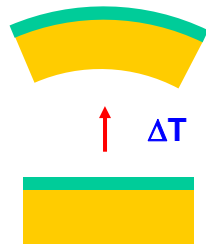
C. Lai, J. Hsieh, and W. Fang, *IEEE Optical MEMS'04*, 2004





## Active component

- Linear thermal actuator

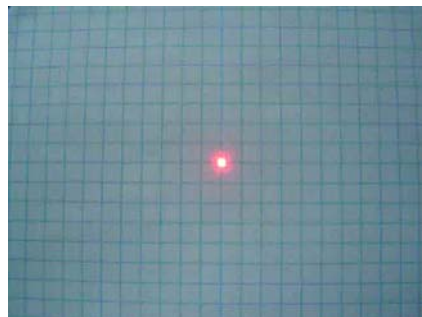
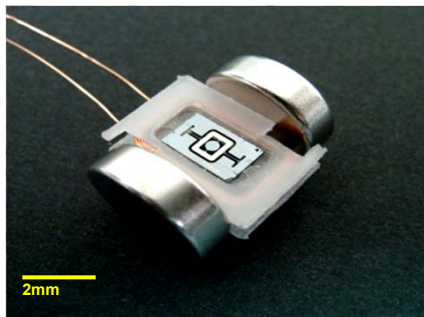
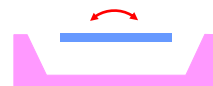


W.-K. Hsu, and W. Fang, *Nanotech*, 2008



## Active component

- Angular magnetic actuator



Yang, and Fang, *JMEMS*, 2007



# 組裝與整合



## Parts Assembly



[amazon.com](https://www.amazon.com)



## Assembly



[www.precisionscalereplicas.com](http://www.precisionscalereplicas.com)

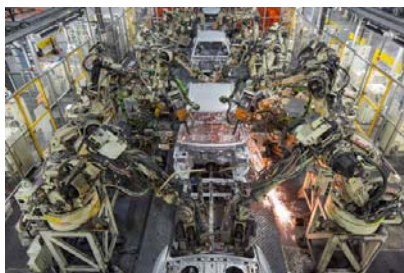


[www.kukausa.com](http://www.kukausa.com)



## Assembly

- Toyota and Foxconn assembly lines



[www.youngertoyota.com](http://www.youngertoyota.com)



[www.zaeke.com](http://www.zaeke.com)



## Assembly

- Boeing 777 assembly lines



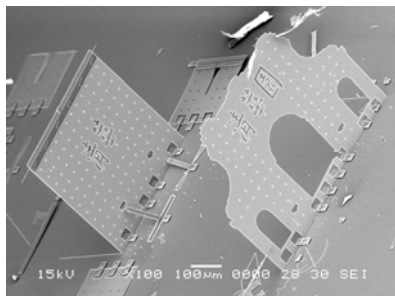
[www.ainonline.com](http://www.ainonline.com)



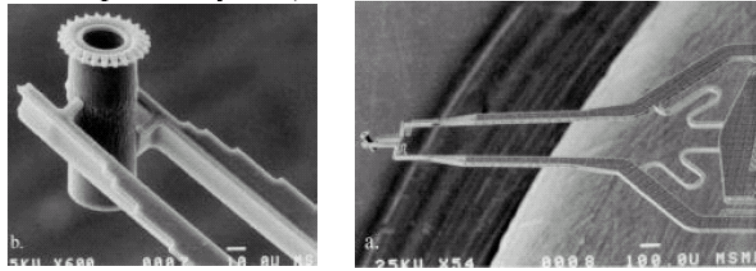
[www.flightglobal.com](http://www.flightglobal.com)



- Manually assembled by probe



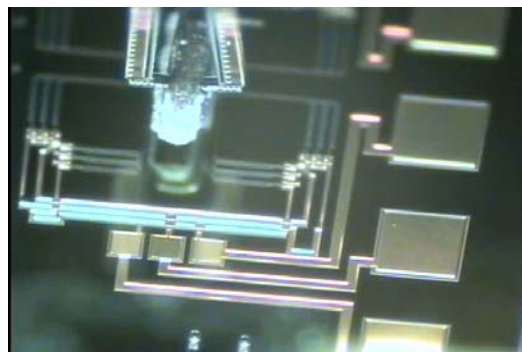
- **Manually assembled by micro gripper**



**Keller, UC Berkeley, 1998**



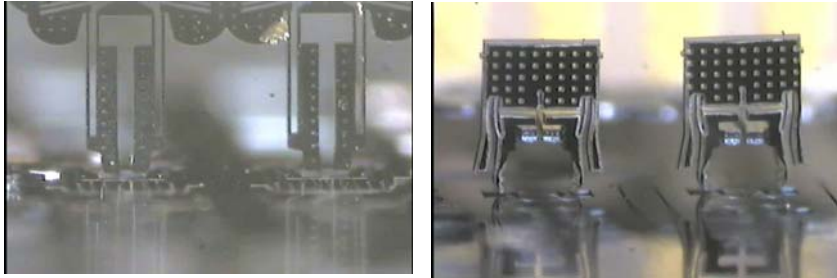
- **Automatically assembled by precision machine**



**Zyvex Inc.**



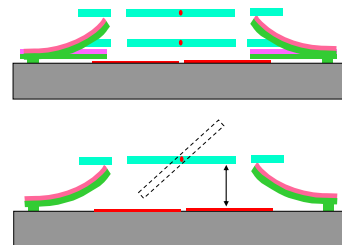
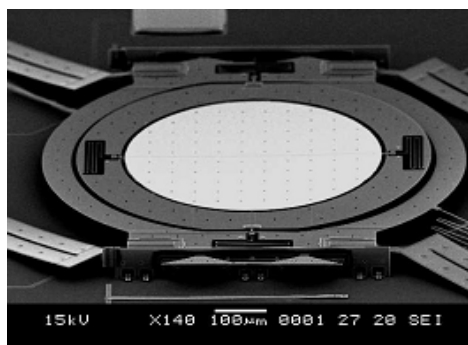
- Automatically assembled by precision machine



Zyvex Inc.

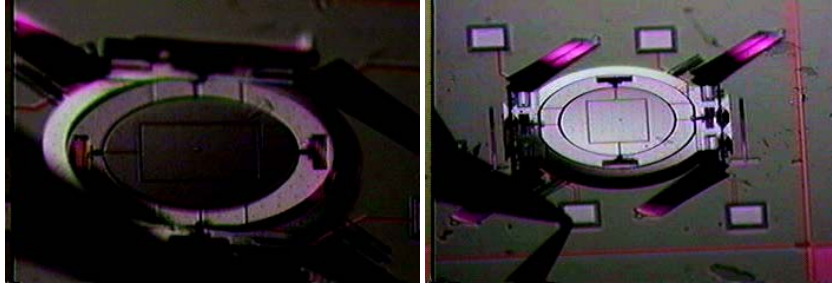


- Self assembly by residual stress deformed beam



Y.-P. Ho, M. Wu, H. Lin, and W. Fang, *IEEE Optical MEMS '02*, 2002





Y.-P. Ho, M. Wu, H. Lin, and W. Fang, *IEEE Optical MEMS '02*, 2002



## About Mechanical Device



<https://www.patek.com/>





## About Mechanical Device



<https://www.patek.com/>



<https://today.line.me/tw>

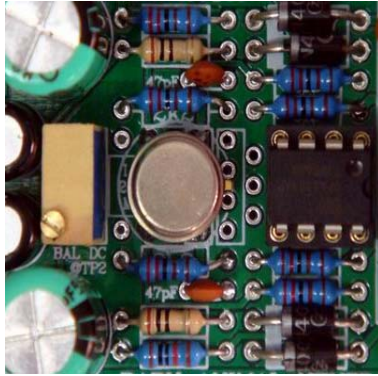
<https://magazine.ncfta.gov.tw/>



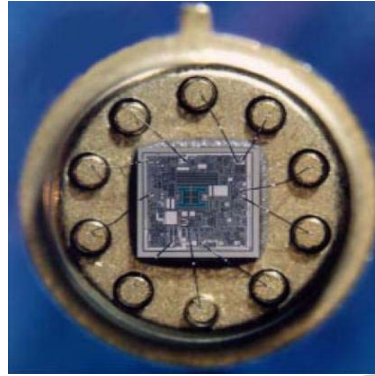


## Process Integration

- **Discrete vs Integrated** electronics components



ATM Elektro, Czech Republic



ADI, USA



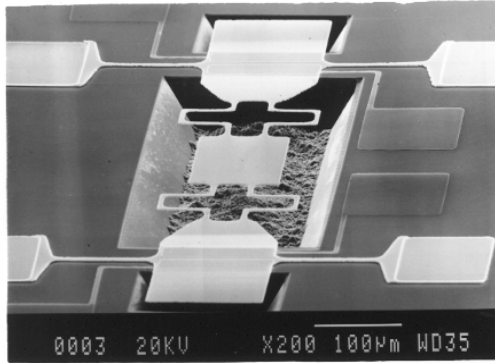
- **Assembly by process integration (一體成形)**



Brigham Young Univ., USA



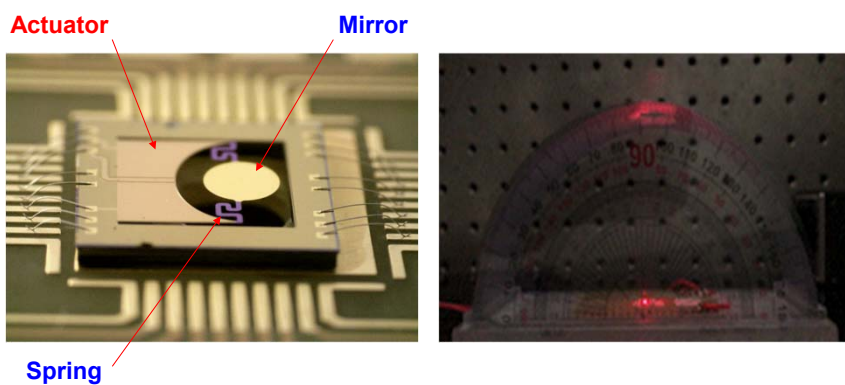
- Assembly by process integration



J. Hsieh and W. Fang, *Transducer'99*, 1999



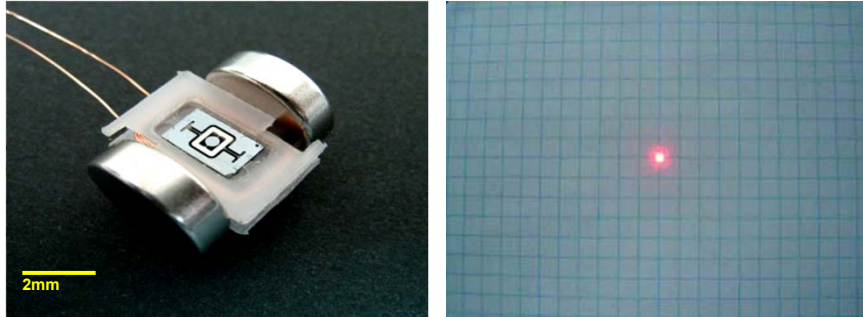
- Assembly by process integration



H. Lin, and W. Fang, *Transducers'23*, Kyoto, Japan, 2023



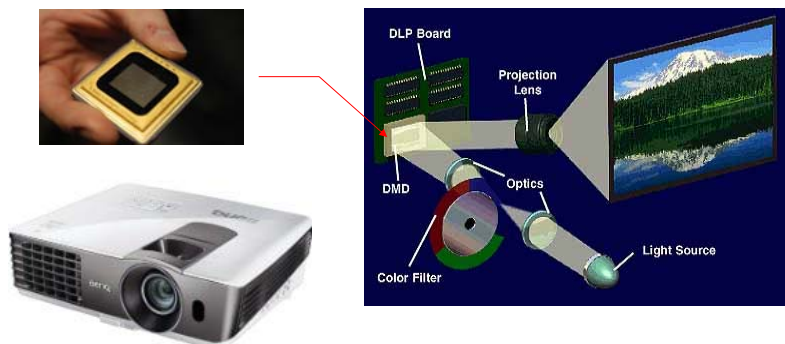
• Scanning images



Yang, and Fang, *JMEMS*, 2007

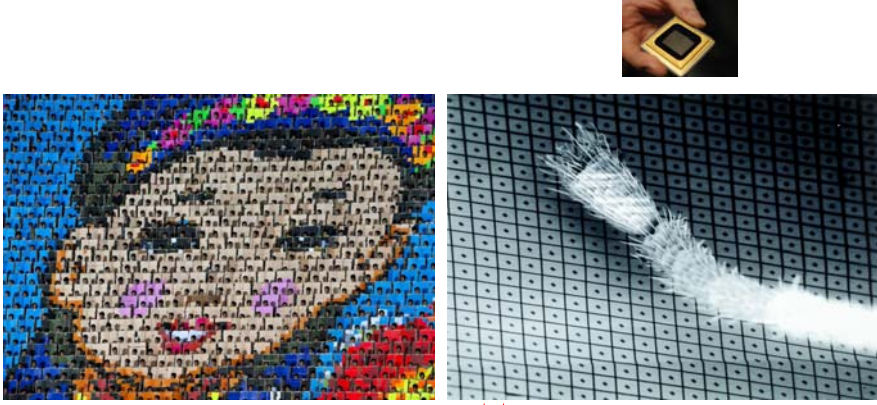


Example - DLP Projector, TI




Texas Instruments Inc.






[www.theatlantic.com](http://www.theatlantic.com) DLP Chip, TI

~15  $\mu\text{m}$



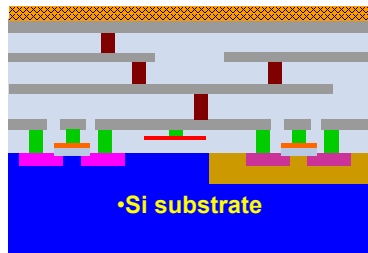
製程平台 - 標準製程



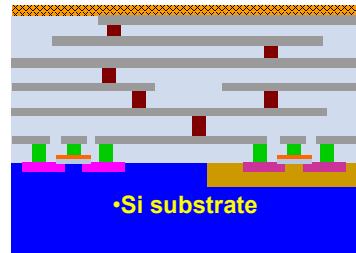
## Standard CMOS Processes

- Available in CMOS foundries: TSMC, UMC, etc...

0.35 $\mu$ m 2P4M CMOS process

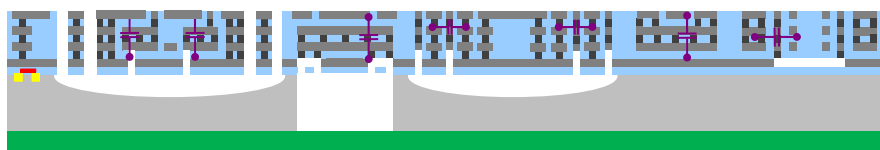


0.18 $\mu$ m 1P6M CMOS process

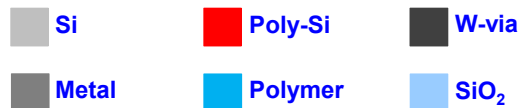


## CMOS-MEMS Platform

Sensing circuit    Tri-axis G sensor    Pressure sensor    Magnetic sensor    Tactile sensor    RF resonator



Standard CMOS process (TSMC 0.35 $\mu$ m)



- Standard TSMC 0.35 $\mu$ m 2P4M CMOS process
- Post-CMOS processes developed by Prof. Fang's group



### 3-axis G-sensor

**Single Z-axis**

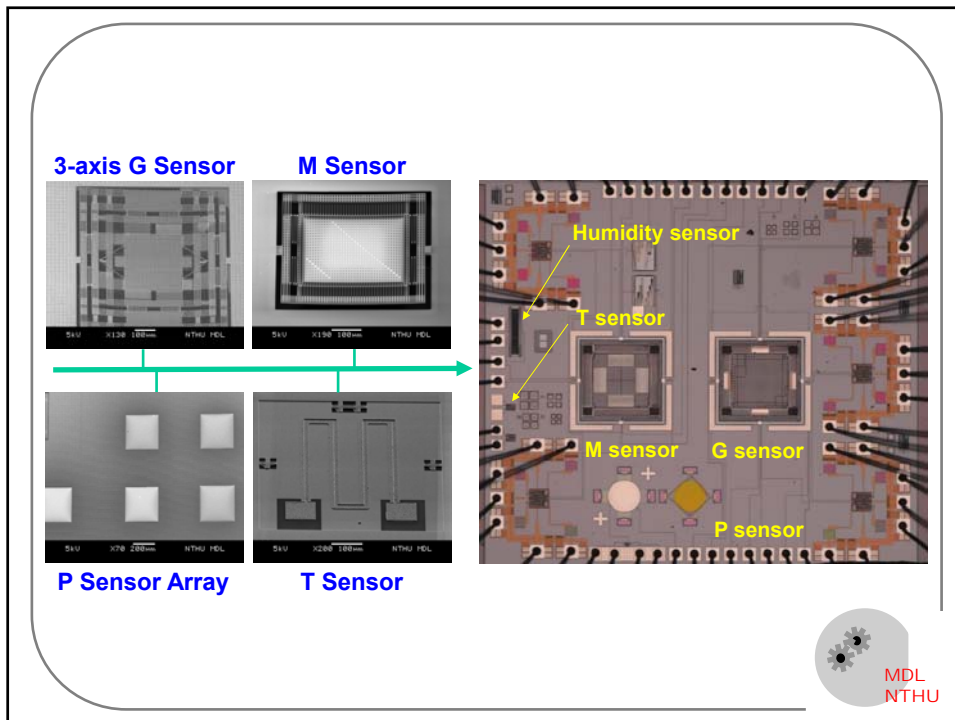
Sun, and Fang, *IEEE MEMS*, 2009  
Sun, and Fang, *IEEE Trans. on ED*, 2010

### Pressure Sensors

**Suspended diaphragm**      **Packaging**

**FIB sectioning**

Sun, and Fang, *Transducers*, 2009  
Sun, and Fang, *JMM*, 2009



## STM THELMA Platform

- Thick Epi-poly Layer for Microactuators and Accelerometers

■ Poly-Si    ■ SiO<sub>2</sub>    ■ Epi-Poly-Si

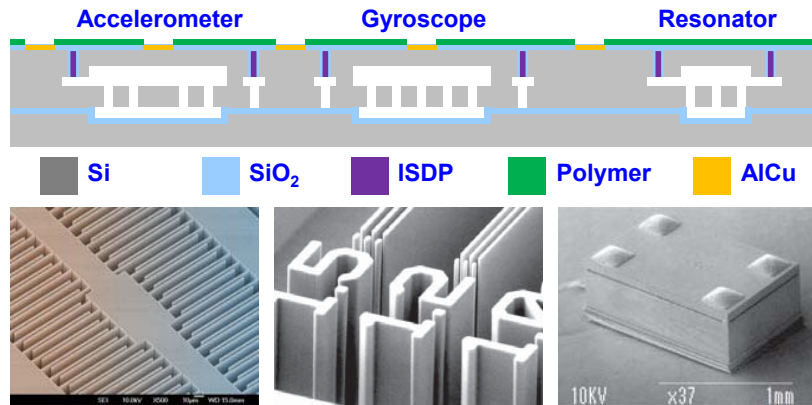
Device  
Contact PADS

<http://www.st.com/>  
G. Langfelder et al., *IEEE Trans. on IE*, 2012

MDL  
NTHU

## Teledyne DALSA MIDIS Platform

- MEMS Integrated Design for Inertial Sensors

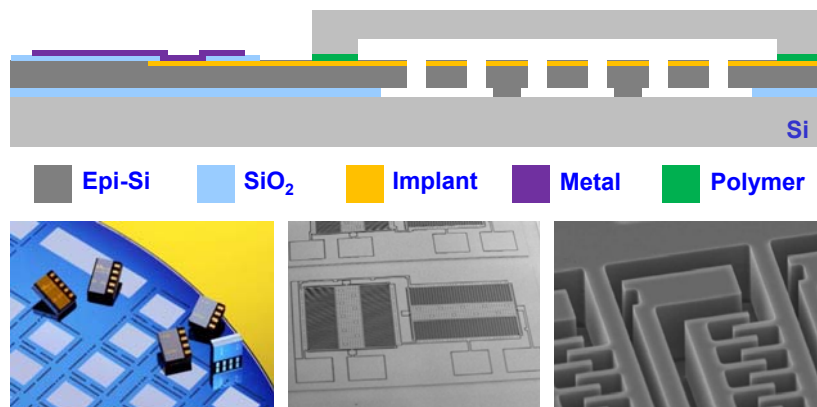


<http://www.teledynedalsa.com/>



## Tronics Platform

- Epi-SOI technology



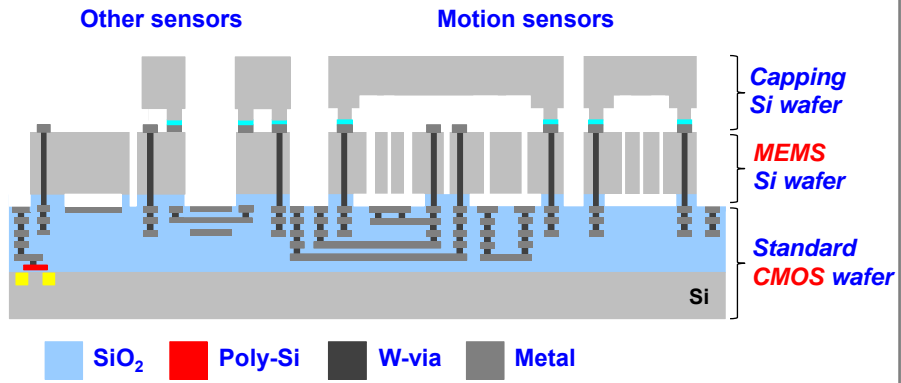
<http://www.tronicsgroup.com/>  
S. Renard, *JMM*, 2000





## TSMC MEMS Platform

- Si-MEMS above CMOS



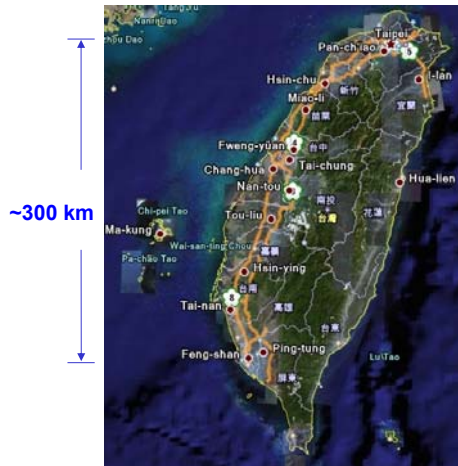
Source : TSMC



## 台灣現況簡介



## About Taiwan



### Taiwan

Area: ~36,000 km<sup>2</sup>  
Population: ~23.4 M

### The Netherlands

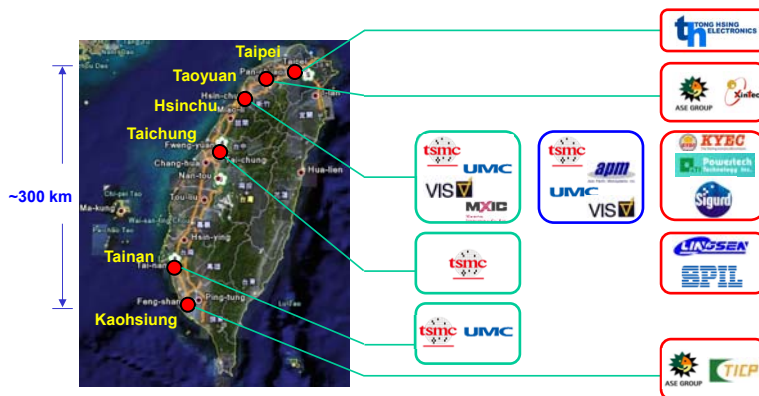
Area: ~41,500 km<sup>2</sup>  
Population: ~16.5 M

### Belgium

Area: ~30,500 km<sup>2</sup>  
Population: ~11.2 M



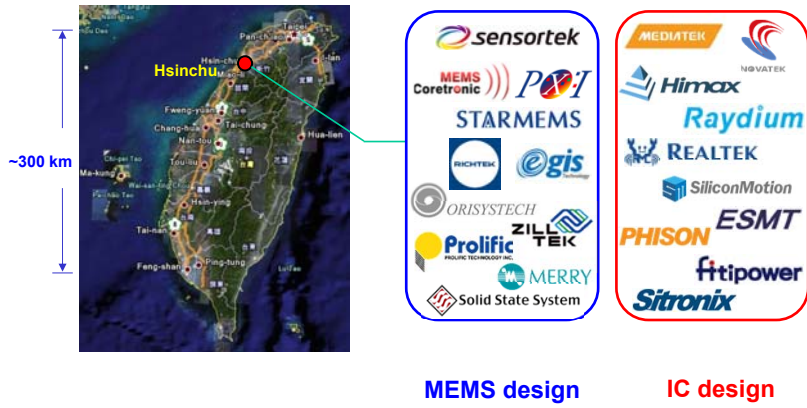
## MEMS Eco-system at Taiwan



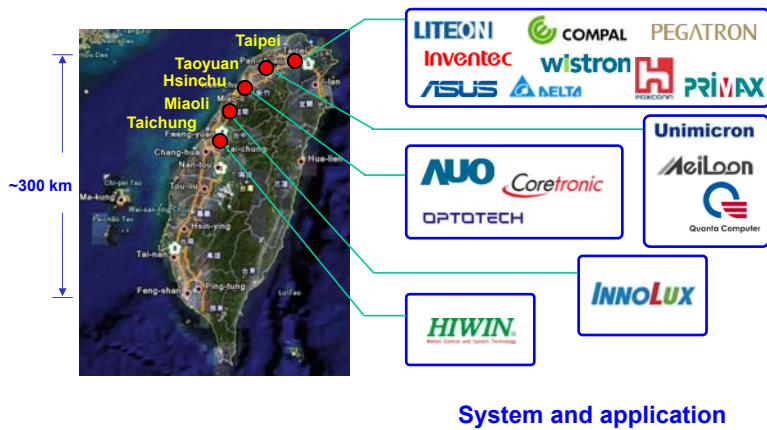
CMOS Fab MEMS Fab Packaging House



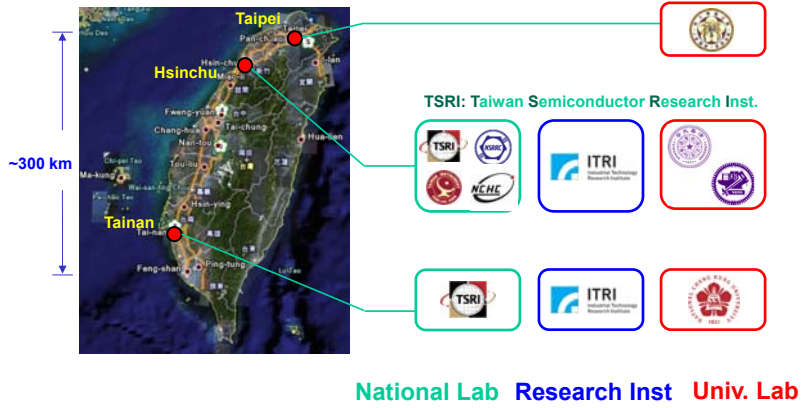
## MEMS Eco-system at Taiwan



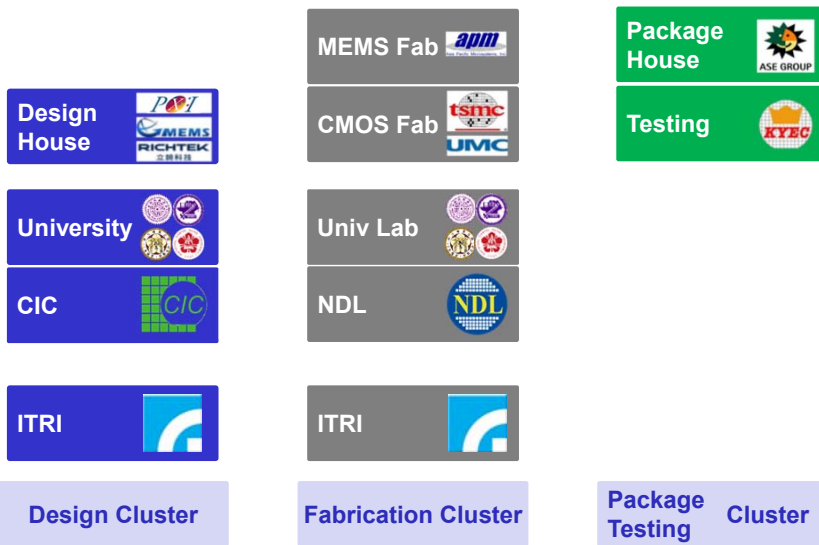
## MEMS Eco-system at Taiwan



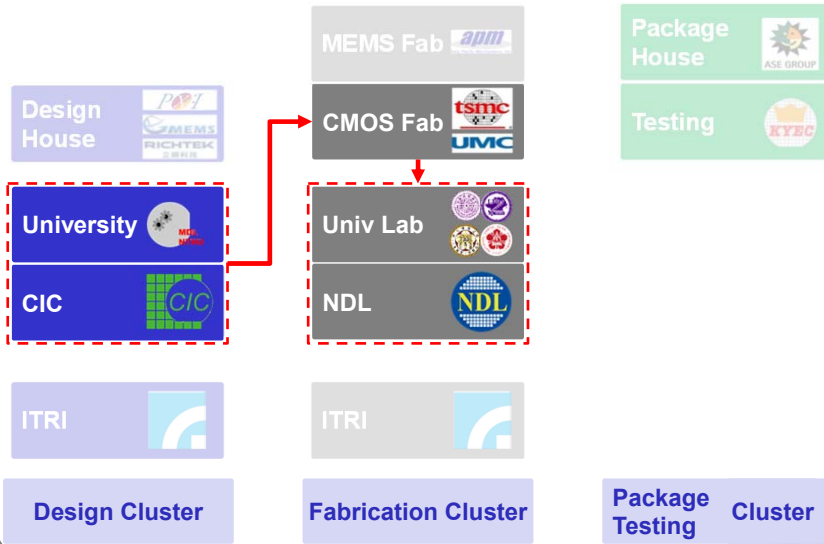
## MEMS Eco-system at Taiwan



## MEMS Networks at Taiwan

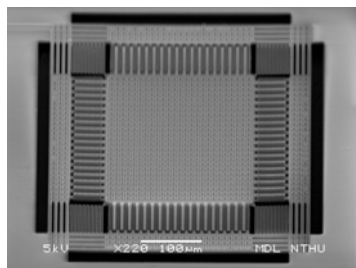


## MEMS Networks at Taiwan

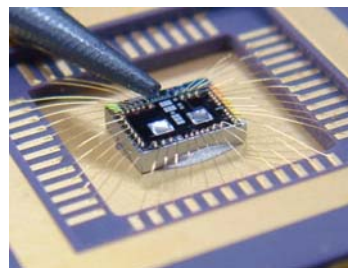


MDL  
NTHU

## 0.18um 1P6M TSMC CMOS Process



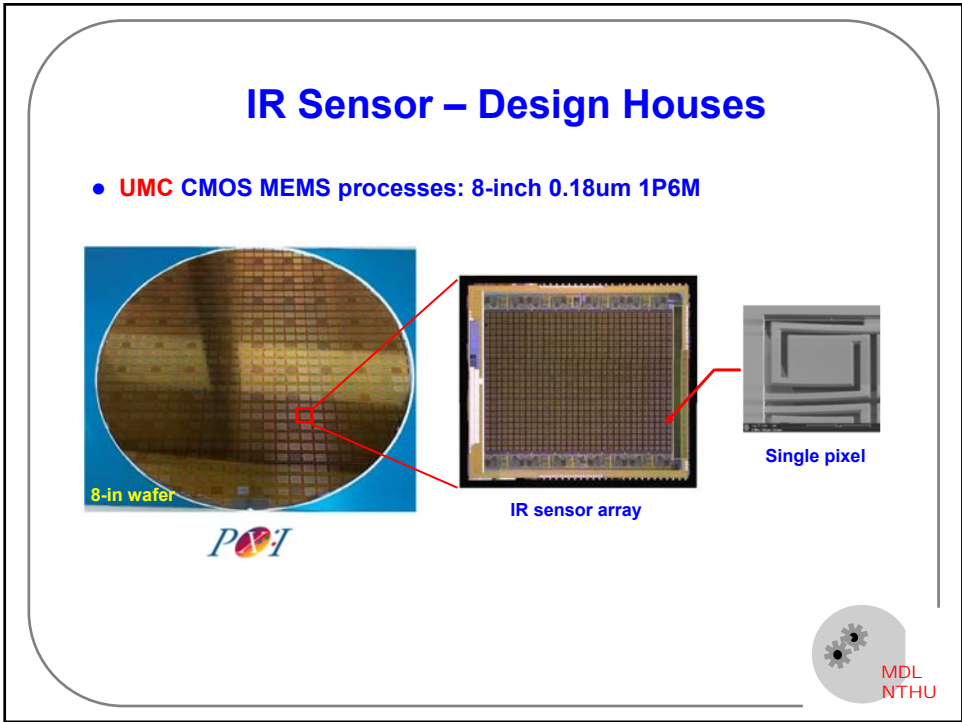
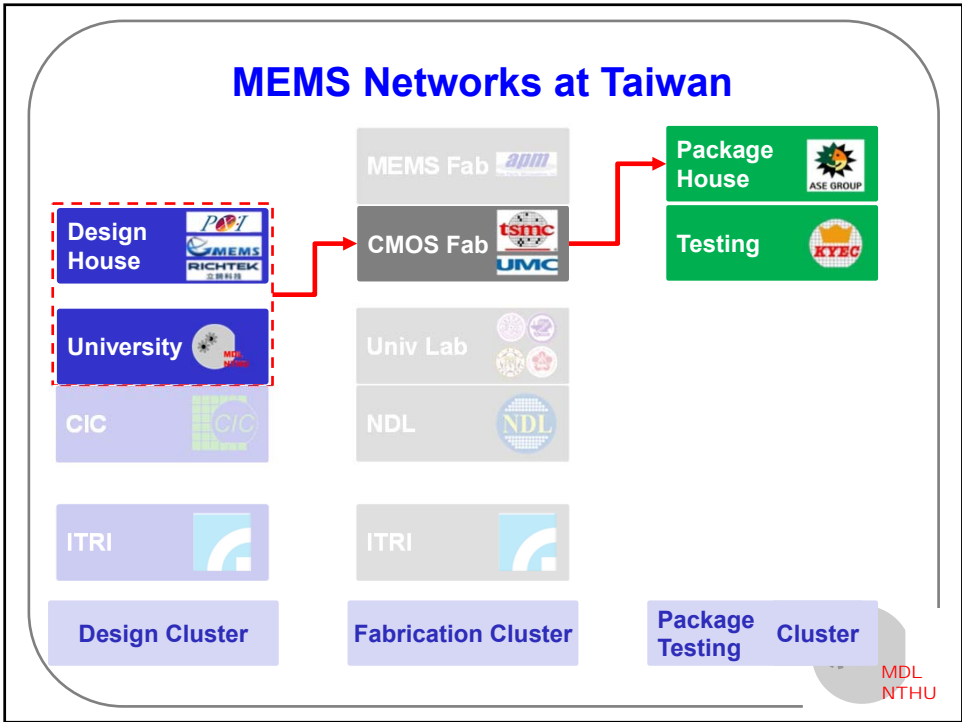
3-axis accelerometer



Sensor after bonding

Sensing-axis	X-axis	Y-axis	Z-axis
Measurement Range (G)	0.01~1	0.01~1	0.01~1
Sensitivity (mV/G)	14.2	14.6	8.0
Non-linearity (%)	3.0%	1.5%	1.8%
Noise (mG/sqrtHz)	1.9	2.9	3.4

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## IR Sensor – Design Houses

- System level integration for data mining/fusion: image + IR sensors

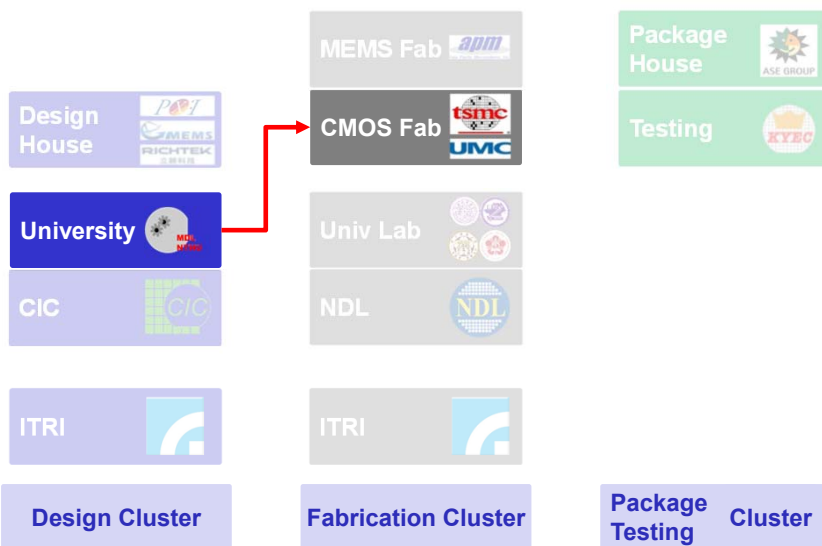


Voice: normal body temp.    Voice: wear mask!

<https://www.eetimes.com/smart-thermal-sensing-creates-machine-intelligent/>

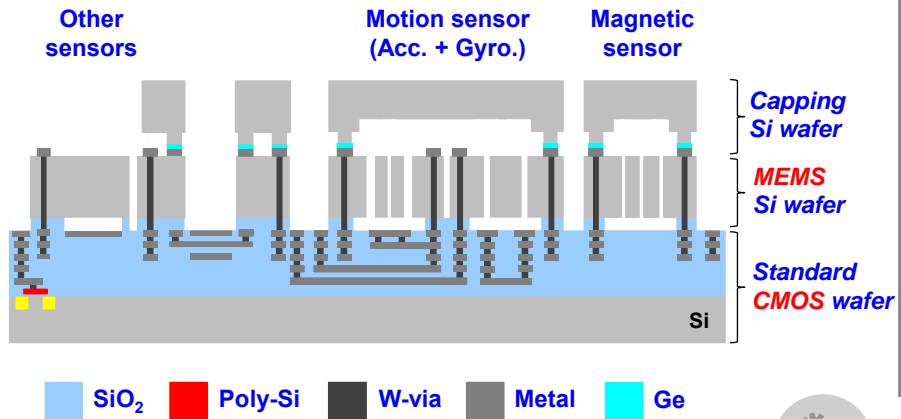


## MEMS Networks at Taiwan



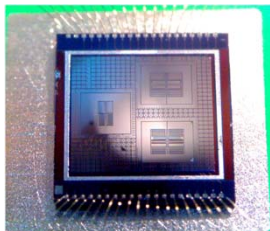
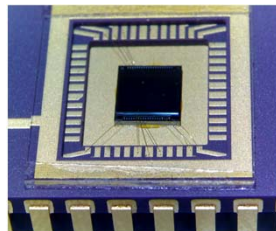
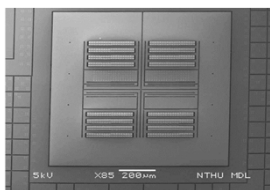
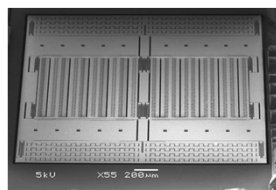
## TSMC MEMS Platform

- **Si-MEMS** above **CMOS**



## TSMC MEMS Platform

- Gyroscope and Magnetic Sensor

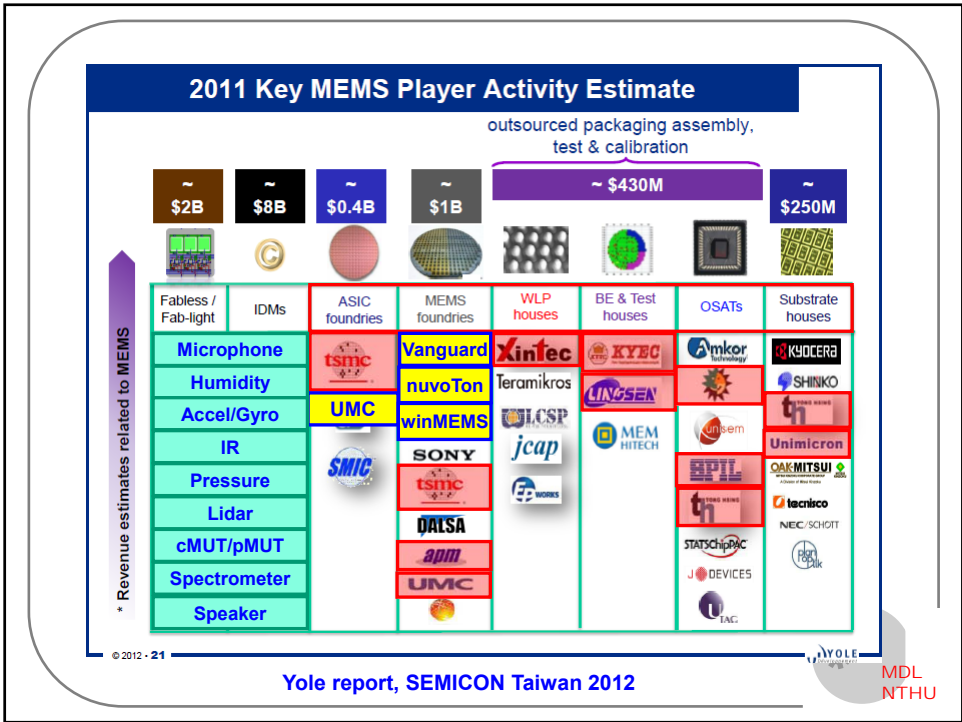


Lee and Fang, *IEEE MEMS*, 2016

Sung and Fang, *IEEE MEMS*, 2016



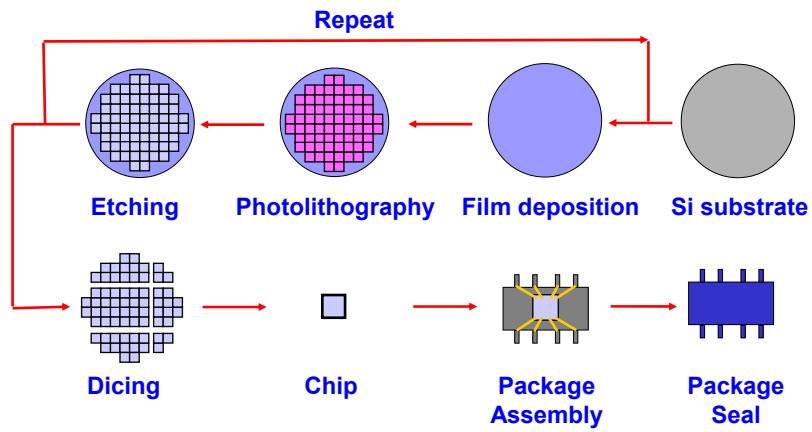




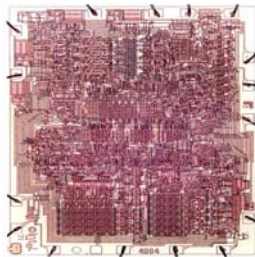
## 結論

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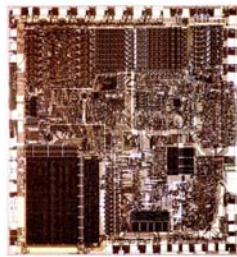
## Semiconductor processes



## Microprocessor



The 4004 – 2.3k transistors, 1971



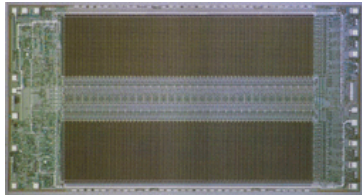
8088/8086 - 29k transistors, 1978



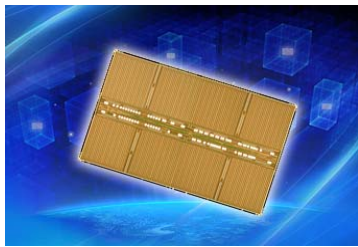
Pentium IV – 42M transistors, 2000



## Memory



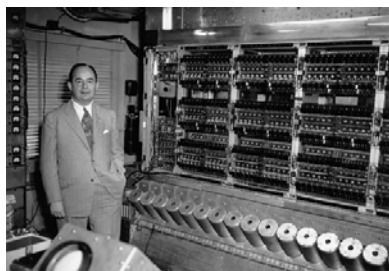
The 16kb DRAM, 1976



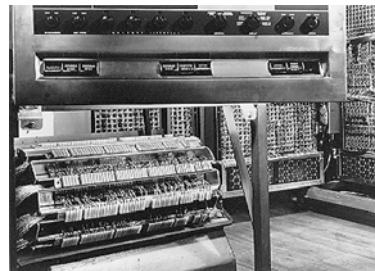
The 2Gb DRAM, 2011



## Computer



von Neumann and his  
"computer", 1952



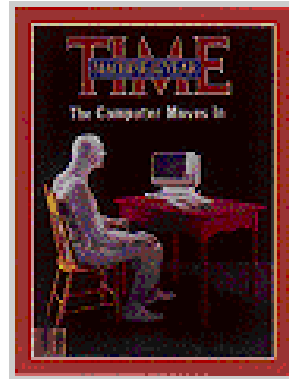
IBM 650, 1954



## Computer



Jobs & Wozniak with Apple II - 1976



IBM PC – 1981/2



## Computer

ENIAC (Vacuum tube)



Mainframes (LSI)



Notebook



Tablet



1946

1965

1992

2010

1960

1975

2004



First Mainframes  
(Transistor)



Person computer  
(VLSI)

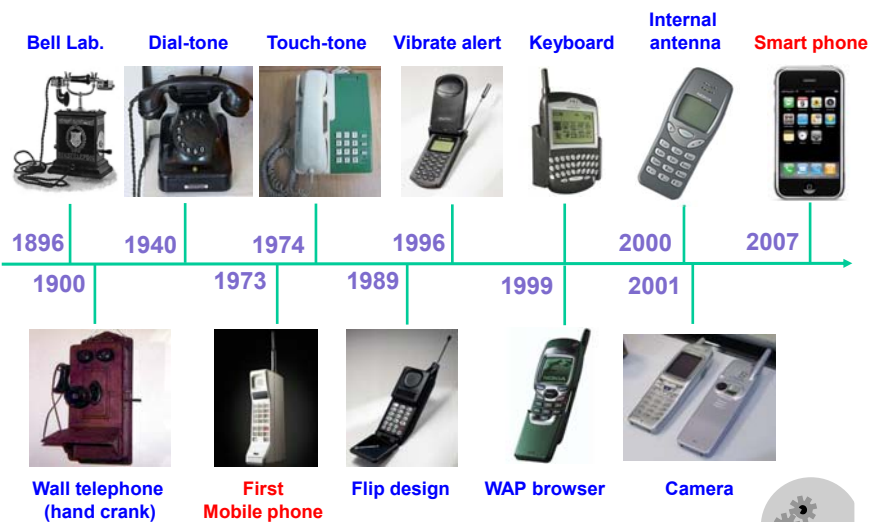


Notebook

Ref: Wiki



# Telephone

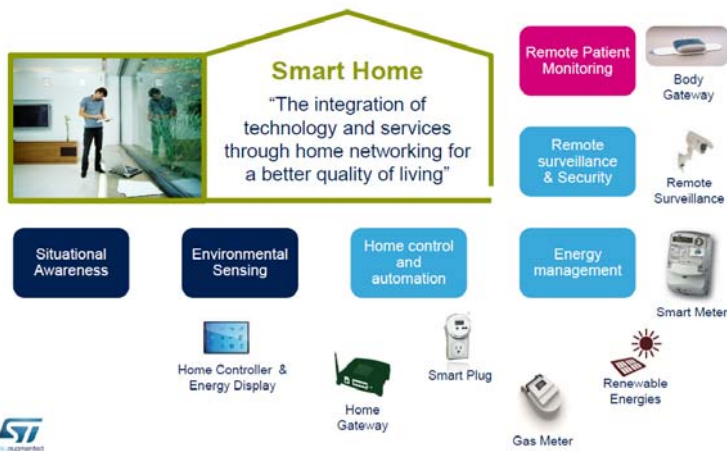


Ref: Wiki

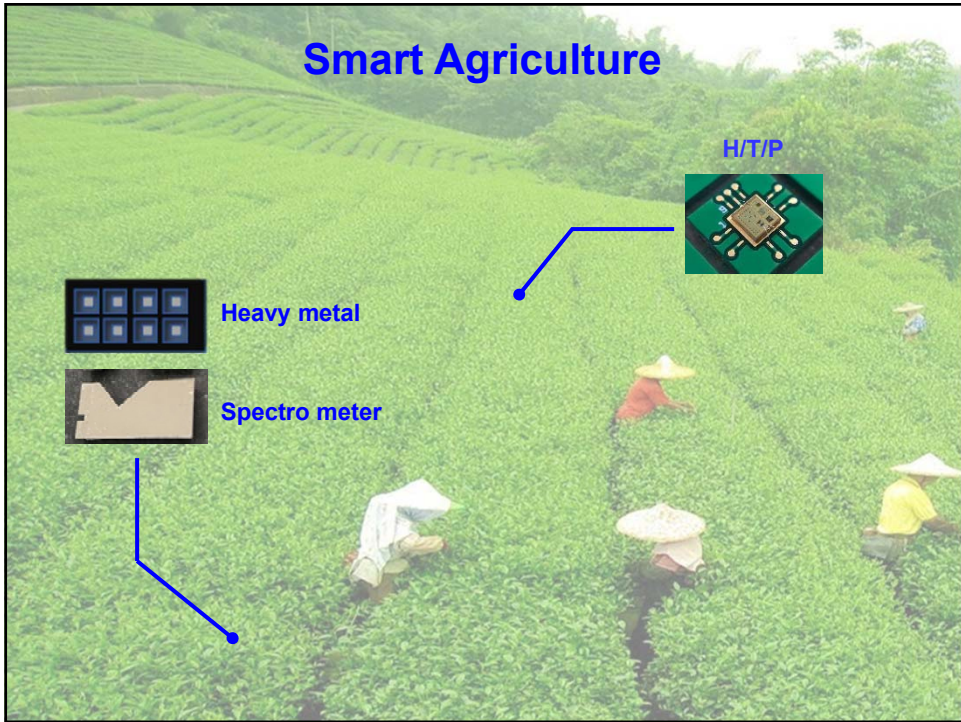
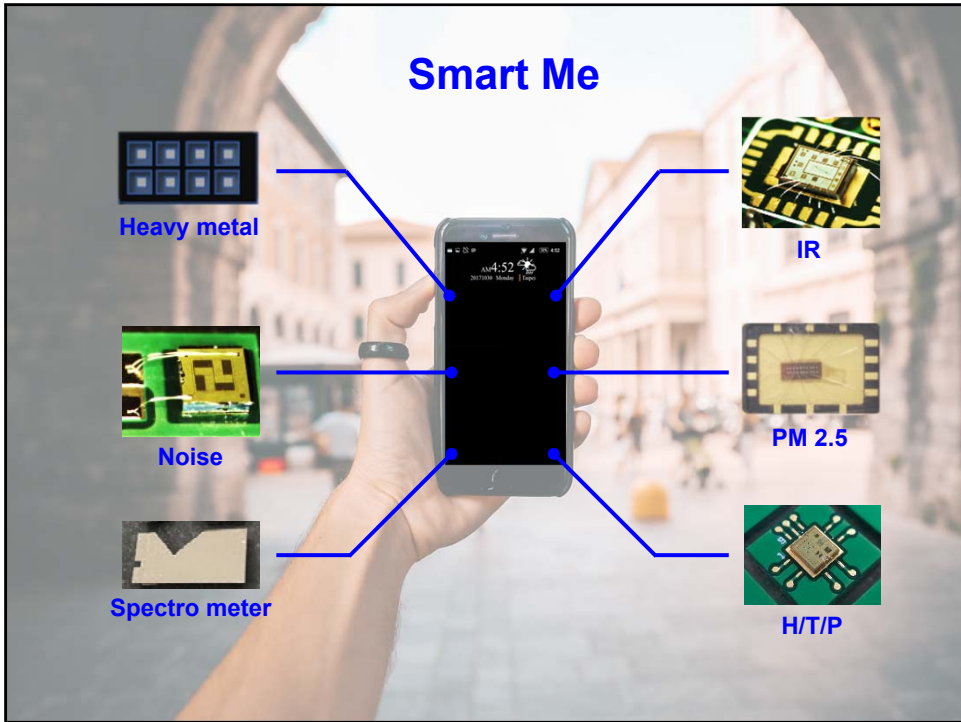


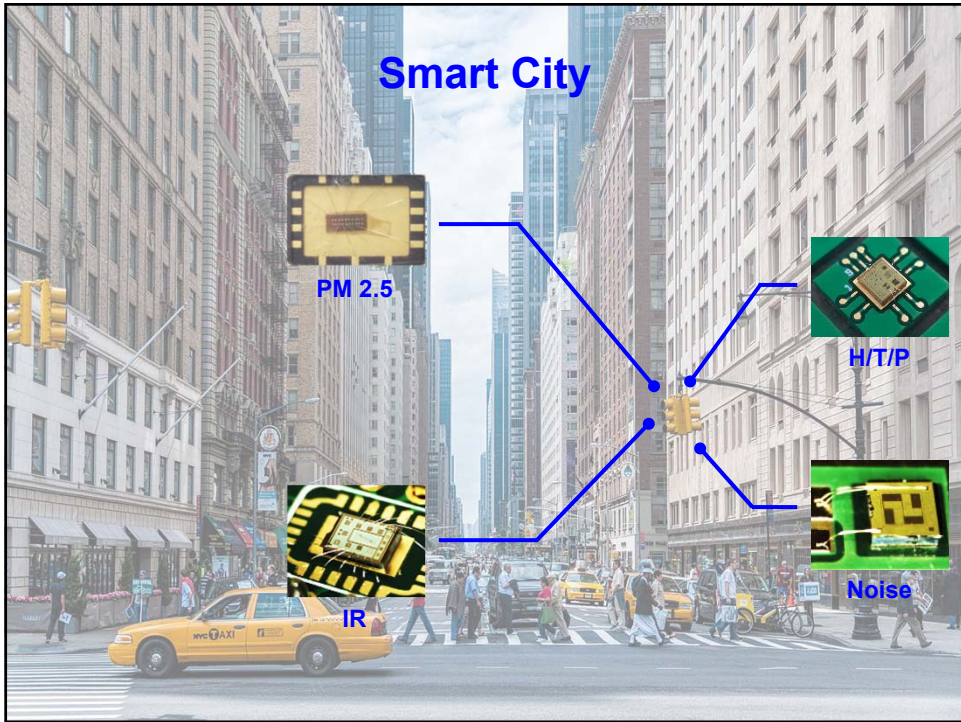
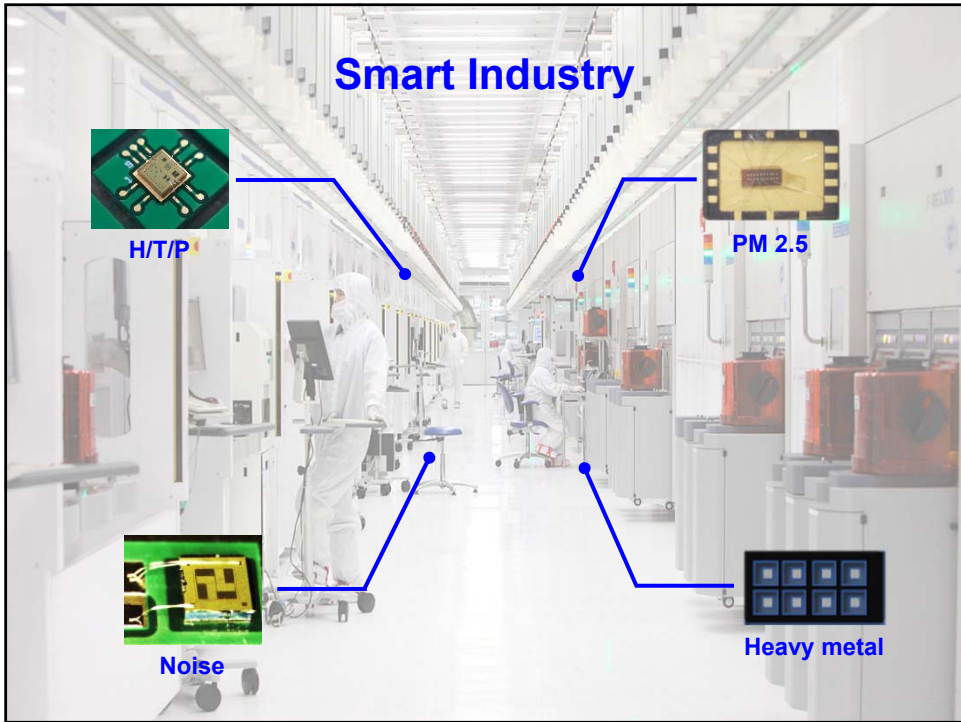
# From IoT to Smart-X

- Internet of Things (IoT)

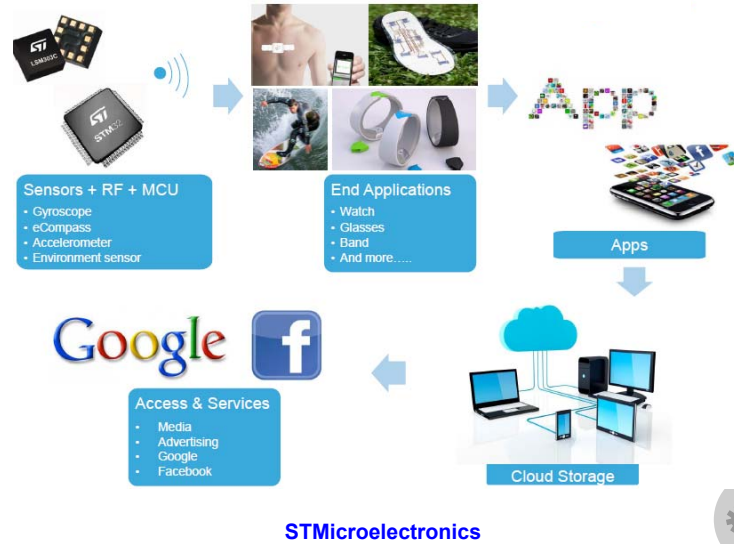








## Ecosystems for IoT



## IoT – the Next Big Things

- The next big things
  - + Highlight by Dr. Morris Chang of TSMC in 2014
  - + Major players: Google, Apple, Cisco, Alibaba, Huawei, etc.
  - + **Semiconductor remain the key enabling tech.**



[www.appledaily.com.tw](http://www.appledaily.com.tw)





## The **PMMP** Era

- **Applications for PMMP** (people-machine-machine-people) Era
  - + Highlight by Dr. Tien Wu of ASE in 2023
  - + Driven by: big data, AI, Autonomous vehicle, etc.
  - + **Future needs: five sense**



<https://udn.com/news/>

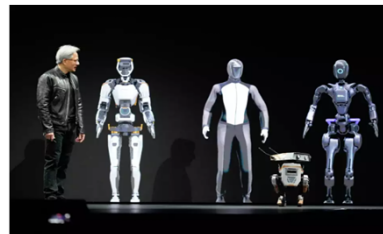


## Humanoid Robots

- Demonstrated by CEO Jensen Huang of Nvidia in 2024
- Once again: “**5 Senses + AI**” for future needs



<https://tw.nextapple.com/>

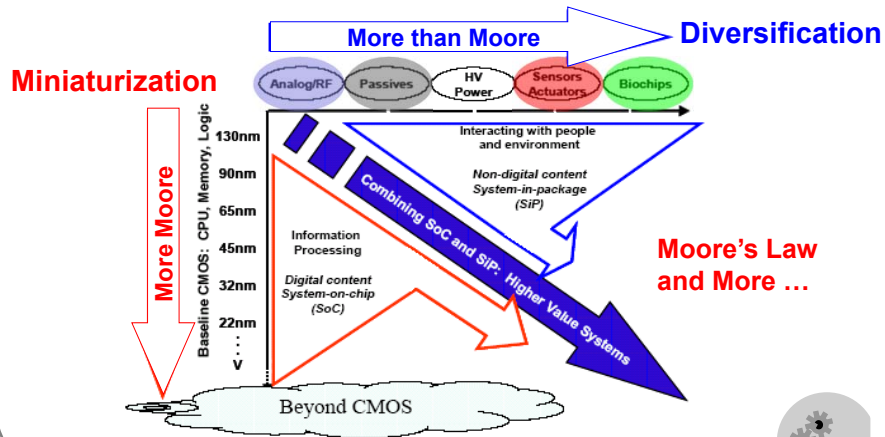


<https://www.sfchronicle.com/>



## More than Moore

- Moore's Law and More – **X on Silicon**
- Add value to the existing CMOS tech



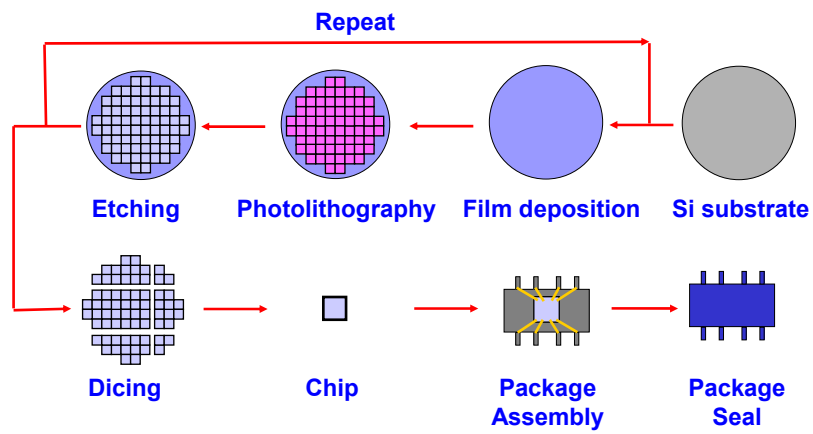
Source: ITRS Roadmap 2005, [www.itrs.net](http://www.itrs.net)



## 課程安排



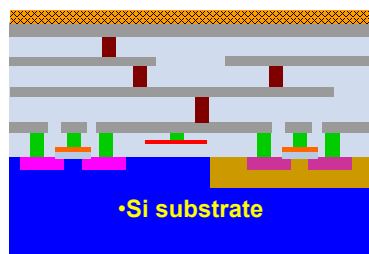
## Semiconductor processes



## Standard CMOS Processes

- Available in CMOS foundries: TSMC, UMC, etc...

0.35 $\mu\text{m}$  2P4M CMOS process



0.18 $\mu\text{m}$  1P6M CMOS process

